

Thermal Putty

➤ Product introduction

GN-Ultimate 4W - component Thermal Putty is a highly adaptable thermal interface material for gap filling. This material is softer and has lower stress than thermal conductive silicone pads, and it can be automatically dispensed and coated. Under appropriate pressure, it can achieve an ultra-thin effect and extremely low thermal resistance, making it the best choice for scenarios where multiple chips share a heat sink/structural component.



➤ Typical Properties

Property	Data	TEST Method
Thermal conductive	4.0W.m ⁻¹ .K ⁻¹	ASTM D5470
Color	Green	Visual
Flow Rate, 30cc syringe with no tip attachment 0.100" orifice, 90psi	15~55 g/min	Direct Test Method
Density	3.3g.cm ⁻³	ASTM D792
Minimum bond line thickness	0.1mm	Direct
Temperature Range	-55°C~+200°C	—
Breakdown Voltage	>6000 V/mm	ASTM D149
Volume Resistivity	10 ¹³ ohm-cm	ASTM D257
Flammability Rating	V-0	UL 94
RoHS Compliant	Yes	Direct Certification
Optimal Storage:	25°C (±10) 50% RH (±10) for 18 months shelf life	

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.

Applications

- Automotive Electronic Control Units
- Heat sink, Memory modules
- LED Lighting, LCD-TV
- Military Electronics
- Power Supplies
- Telecom services
- Wireless instruments
- Automotive control services

Features and Benefits

- High thermal conductivity
- Easily dispensable
- Natural tacky & Low contact resistance
- Full-cured & No oil-bleeding
- High compression
- Suit auto-dispensing equipment
- Meets Rohs specification